

N-Channel Super Junction Power MOSFET

General Description

The series of devices use advanced super junction technology and design to provide excellent R_{DS(ON)} with low gate charge. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, and industrial power applications.

Features

- •New technology for high voltage device
- Low on-resistance and low conduction losses
- Small package
- ●Ultra Low Gate Charge cause lower driving requirements
- ●100% Avalanche Tested
- ROHS compliant

Application

- Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply (UPS)

Package Marking And Ordering Information

Device	Device Package	Marking	
NCE05N50L	TO-251S	NCE05N50	



V_{DS} @T_{jmax}

R_{DS(ON)}

 $I_{\rm D}$

GC

560

900

5

V

mΩ

А

D

S

Schematic diagram



Table 1. Absolute Maximum Ratings (T_c=25℃)

Parameter	Symbol	NCE05N50L	Unit
Drain-Source Voltage (VGs=0V)	Vds	500	V
Gate-Source Voltage (VDs=0V)	Vgs	±30	V
Continuous Drain Current at Tc=25°C	I _{D (DC)}	5	A
Continuous Drain Current at Tc=100°C	I _{D (DC)}	3	А
Pulsed drain current (Note 1)	DM (pluse)	15	A
Drain Source voltage slope, VDS = 400 V, ID = 5 A, Tj =	dv/dt	50	V/ns
125 °C	uviat	30	V/115
Maximum Power Dissipation(Tc=25°C)	PD	50	W
Derate above 25°C		0.4	W/°C
Single pulse avalanche energy (Note2)	Eas	130	mJ
Avalanche current ^(Note 1)	I _{AR}	5	А





Parameter	Symbol	Value	Unit mJ °C	
Repetitive Avalanche energy , t_{AR} limited by T_{jmax} (Note 1)	E _{AR}	0.4		
Operating Junction and Storage Temperature Range	T _J ,T _{STG}	-55+150		
Table 2. Thermal Characteristic				
Parameter	Symbol	NCE05N60L	Unit	
Thermal Resistance, Junction-to-Case (Maximum)	R _{thJC}	2.5	°C /W	
Thermal Resistance, Junction-to-Ambient (Maximum)	R _{thJA}	75	°C /W	

Table 3. Electrical Characteristics (TA=25[°]Cunless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
On/off states			•			
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250µA	500			V
Zero Gate Voltage Drain Current(Tc=25℃)	I _{DSS}	V _{DS} =500V,V _{GS} =0V			1	μA
Zero Gate Voltage Drain Current(Tc=125℃)	I _{DSS}	V _{DS} =500V,V _{GS} =0V			50	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±30V,V _{DS} =0V			±100	nA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =250µA	2.5	3	3.5	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =3A		850	900	mΩ
Dynamic Characteristics						
Forward Transconductance	g fs	V _{DS} = 20V, I _D =3A		5		S
Input Capacitance	C _{lss})/ _ = = 0)// ()/ _ = 0)/		520		PF
Output Capacitance	Coss	V _{DS} =50V,V _{GS} =0V, F=1.0MHz		52		PF
Reverse Transfer Capacitance	C _{rss}			4.5		PF
Total Gate Charge	Qg)/ _100)// _54		13	25	nC
Gate-Source Charge	Q _{gs}	V _{DS} =400V,I _D =5A, V _{GS} =10V		2.2		nC
Gate-Drain Charge	Q _{gd}	V _{GS} =10V		5		nC
Intrinsic gate resistance	R _G	f = 1 MHz open drain		2.6		Ω
Switching times						
Turn-on Delay Time	t _{d(on)}			6		nS
Turn-on Rise Time	tr	V _{DD} =380V,I _D =5A,		2.5		nS
Turn-Off Delay Time	t _{d(off)}	R _G =18Ω,V _{GS} =10V		55	80	nS
Turn-Off Fall Time	t _f			9	14	nS
Source- Drain Diode Characteristics						
Source-drain current(Body Diode)	I _{SD}	T -25°C			5	А
Pulsed Source-drain current(Body Diode)	I _{SDM}	T _C =25°C			15	А
Forward on voltage	V _{SD}	Tj=25°C,I _{SD} =5A,V _{GS} =0V		1	1.3	V
Reverse Recovery Time	t _{rr}	 Tj=25°C,I _F =5A,di/dt=100A/µs		200		nS
Reverse Recovery Charge	Qrr			1.6		uC
Peak reverse recovery current	I _{rrm}			15		А

Notes: 1.Repetitive Rating: Pulse width limited by maximum junction temperature

2. Tj=25°C,VDD=50V,VG=10V, R_G=25 Ω



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)

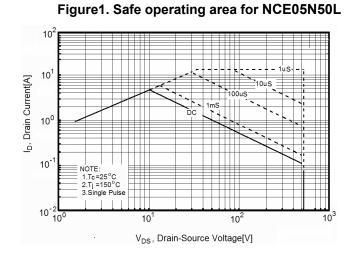


Figure3. Output characteristics

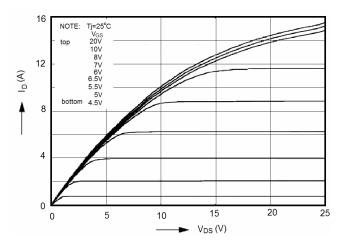


Figure5. Static drain-source on resistance

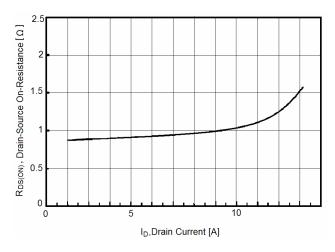


Figure2. Source-Drain Diode Forward Voltage

Figure4. Transfer characteristics

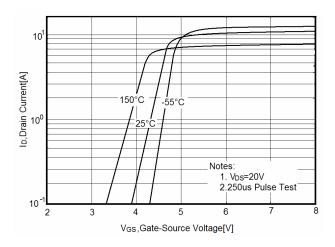


Figure6. R_{DS(ON)} vs Junction Temperature

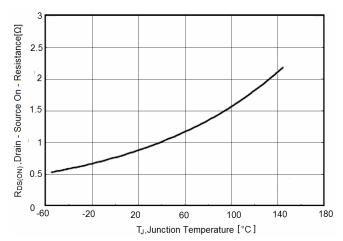




Figure7. BV_{DSS} vs Junction Temperature

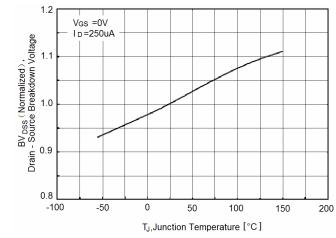


Figure9. Gate charge waveforms

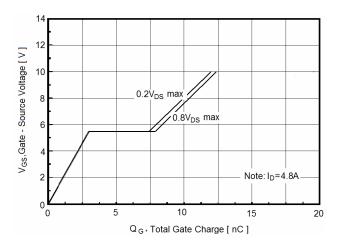


Figure11. Transient Thermal Impedance for NCE05N50L

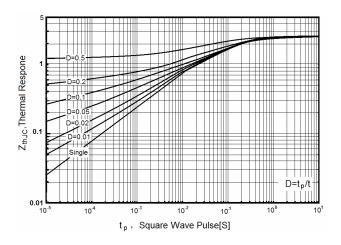


Figure8. Maximum I_{D} vs Junction Temperature

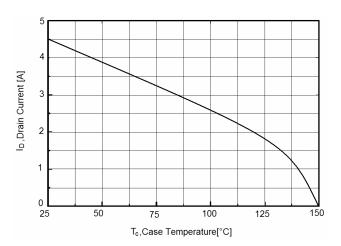
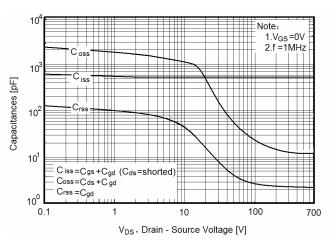


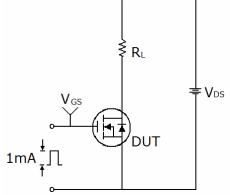
Figure10. Capacitance

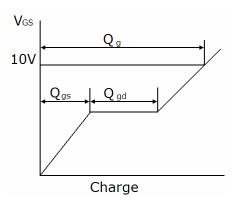




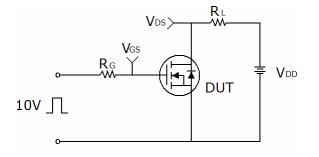
Test circuit

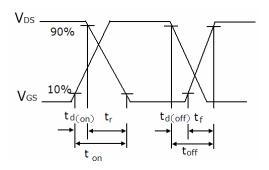
1) Gate charge test circuit & Waveform



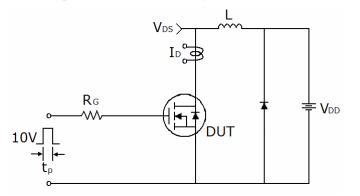


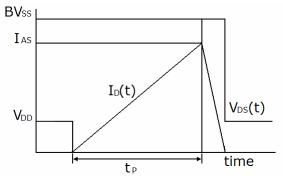
2) Switch Time Test Circuit:





3) Unclamped Inductive Switching Test Circuit & Waveforms

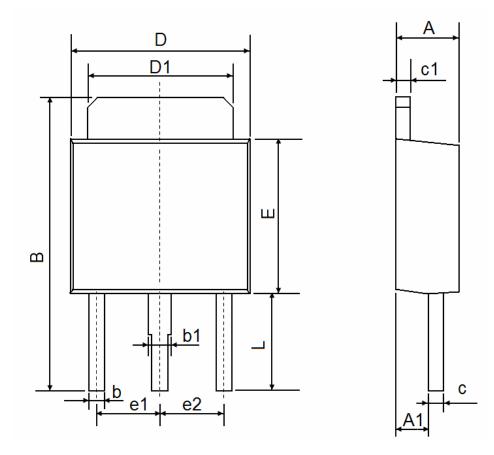








TO-251S Package Information



Symbol	Dimensions	In Millimeters	Dimensions In Inches		
	Min.	Max.	Min.	Max.	
A	2.250	2.350	0.089	0.093	
A1	1.150	1.250	0.045	0.049	
В	10.200	10.800	0.402	0.425	
b	0.550	0.650	0.022	0.026	
b1	0.750	0.850	0.030	0.033	
с	0.480	0.540	0.019	0.021	
c1	0.480	0.540	0.019	0.021	
D	6.400	6.600	0.252	0.260	
D1	5.250	5.350	0.207	0.211	
E	5.400	5.600	0.213	0.220	
e1	2.300 TYP		0.091 TYP		
e2	2.300 TYP		0.091 TYP		
L	3.300	3.700	0.130	0.146	



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